

ABSTRACT

Disclosed is a method and apparatus for coating liquid films on to the surface of a wafer substrate by rotating the substrate at a speed sufficient to cause a liquid, through centrifugal effect, to flow outwardly toward the perimeter of the surface and form a substantially uniform thickness liquid coating thereon and starting at the central region of the wafer surface and moving radially outward therefrom, spraying a fine mist of the liquid to the surface of the wafer.